

QIAOXIN N-Channel Enhancement Mode Power MOSFET

Description

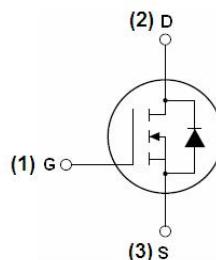
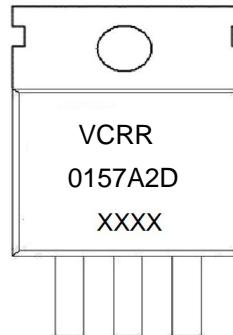
The VCRR0157A2D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- $V_{DS} = 100V, I_D = 57A$
- $R_{DS(ON)} < 12.5m\Omega @ V_{GS}=10V$ (Typ:14.5m Ω)
- Special process technology for high ESD capability
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

**Schematic diagram****Marking and pin assignment****TO-263-2L top view****Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VCRR0157A2D		TO-263-2L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	57	A
Drain Current-Continuous($T_c=100^\circ C$)	$I_D (100^\circ C)$	40	A
Pulsed Drain Current	I_{DM}	160	A
Maximum Power Dissipation	P_D	160	W
Derating factor	-	1.06	W/ $^\circ C$
Single pulse avalanche energy (Note 5)	E_{AS}	580	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	0.94	°C/W
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Electrical Characteristics (T_c=25°C unless otherwise noted)

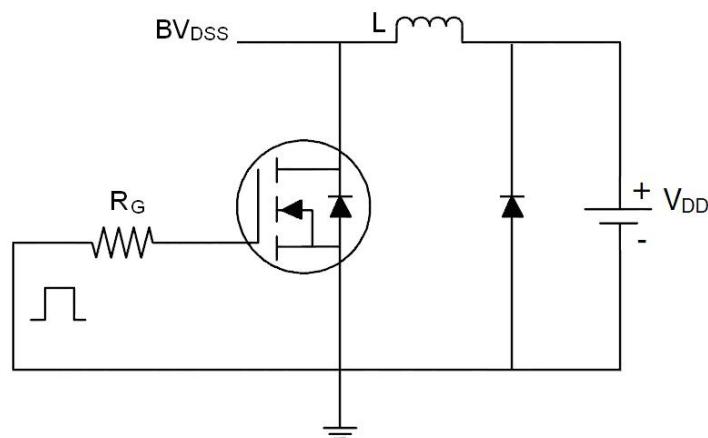
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Drain-Source On-State Resistance	R _{Ds(ON)}	V _{GS} =10V, I _D =28A	-	12.5	14.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} =25V, I _D =28A	32	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1.0MHz	-	3969	-	PF
Output Capacitance	C _{oss}		-	182.5	-	PF
Reverse Transfer Capacitance	C _{rss}		-	160.2	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, I _D =2A, R _L =15Ω V _{GS} =10V, R _G =2.5Ω	-	17	-	nS
Turn-on Rise Time	t _r		-	13	-	nS
Turn-Off Delay Time	t _{d(off)}		-	55	-	nS
Turn-Off Fall Time	t _f		-	16	-	nS
Total Gate Charge	Q _g	V _{DS} =30V, I _D =30A, V _{GS} =10V	-	146.1	-	nC
Gate-Source Charge	Q _{gs}		-	29.3	-	nC
Gate-Drain Charge	Q _{gd}		-	57.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V, I _S =28A	-	0.85	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	57	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, IF = 28A di/dt = 100A/μs ^(Note 3)	-	35	-	nS
Reverse Recovery Charge	Q _{rr}		-	58	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

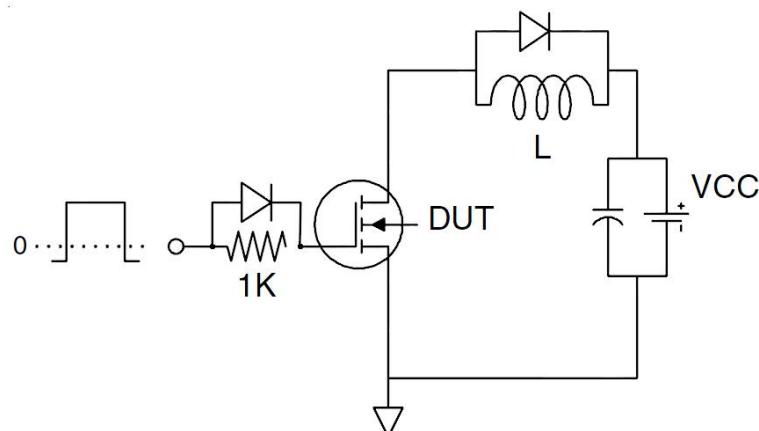
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition: T_j=25°C, V_{DD}=50V, V_G=10V, R_G=25Ω, L=1mH, I_{AS}=35A

Test Circuit

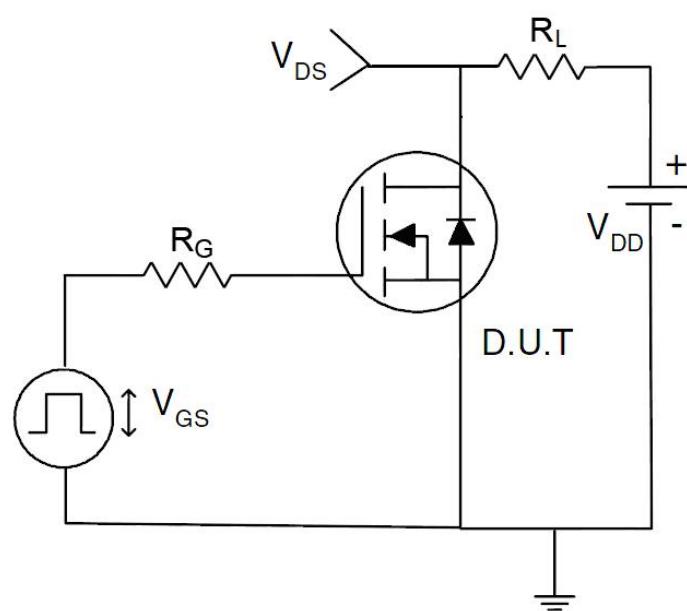
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

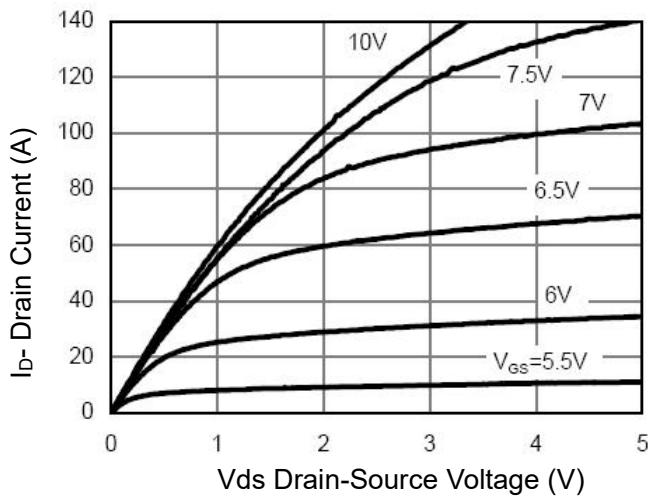


Figure 1 Output Characteristics

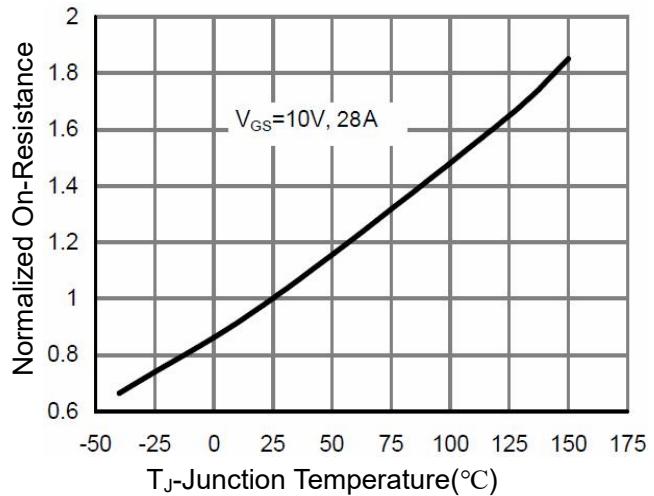


Figure 4 Rdson-Junction Temperature

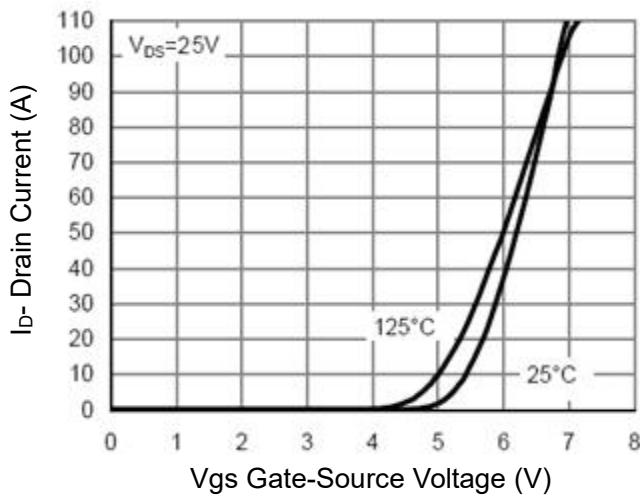


Figure 2 Transfer Characteristics

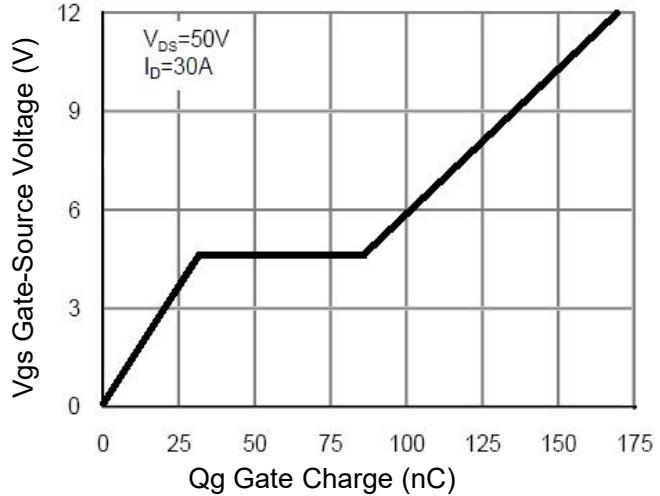


Figure 5 Gate Charge

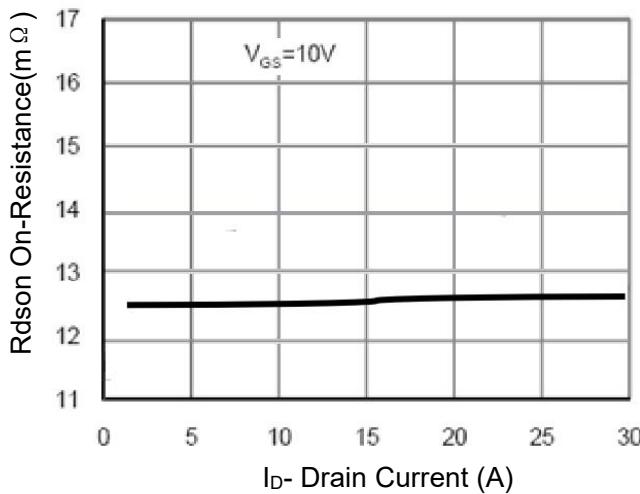


Figure 3 Rdson- Drain Current

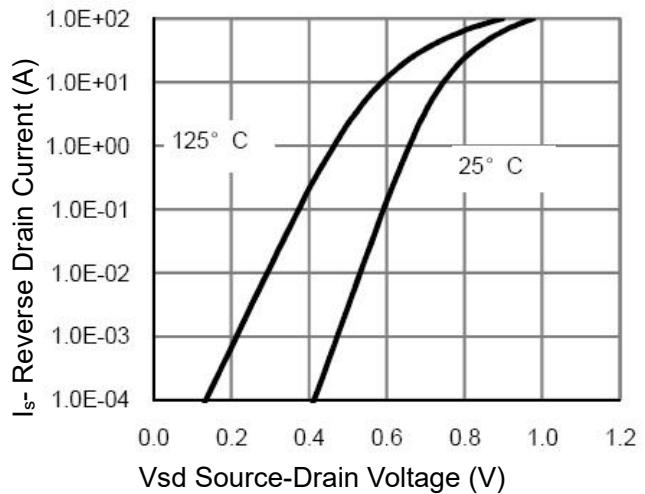


Figure 6 Source- Drain Diode Forward

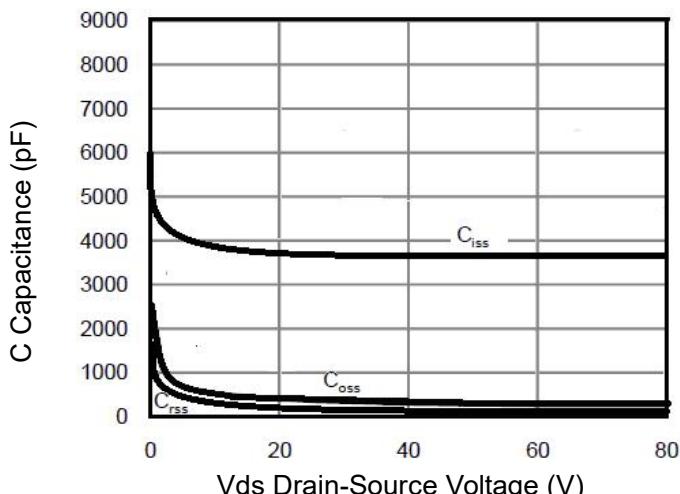


Figure 7 Capacitance vs Vds

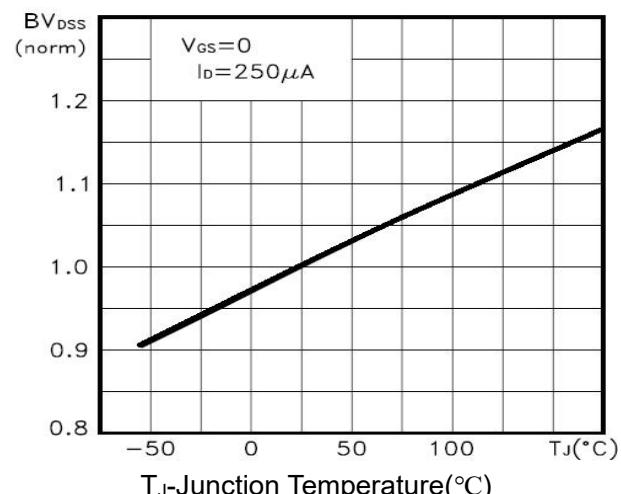


Figure 9 BV_{DSS} vs Junction Temperature

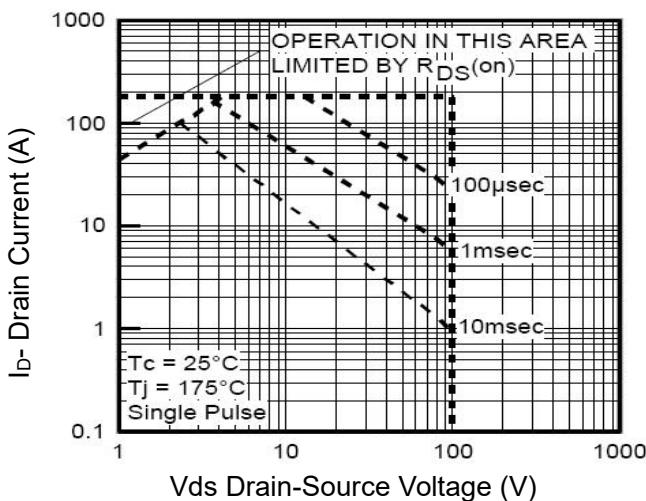


Figure 8 Safe Operation Area

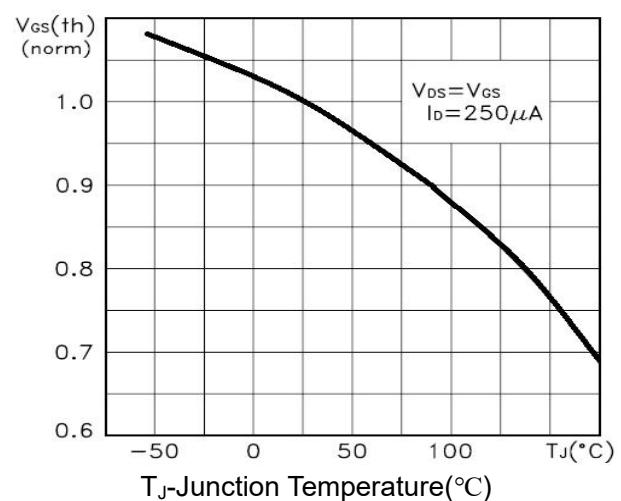


Figure 10 $V_{GS(\text{th})}$ vs Junction Temperature

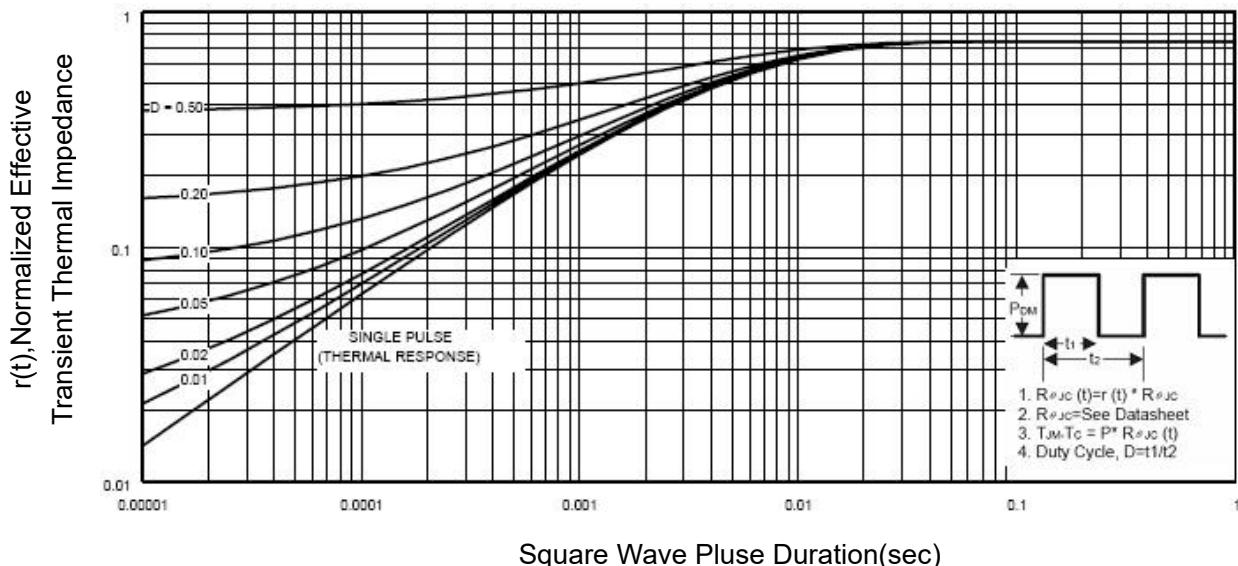
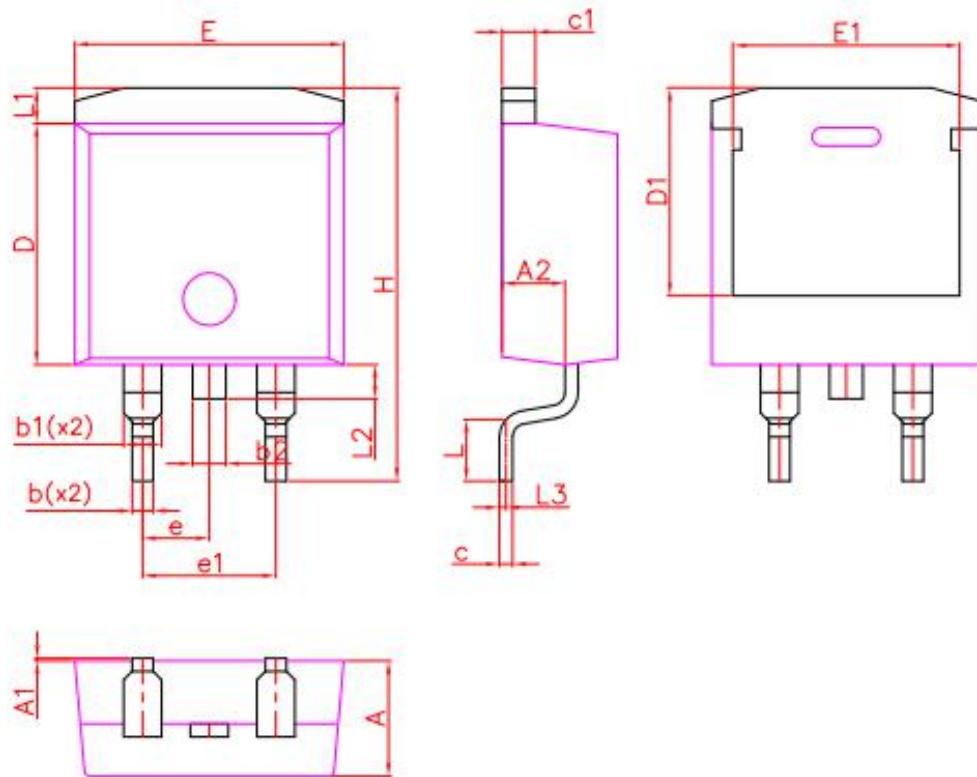


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-263-2L Package Information



TO263			
DIM.	MIN.	NOM.	MAX.
A	4.20	4.40	4.60
A1	0.00	0.10	0.25
A2	2.20	2.40	2.60
b	0.70	0.80	0.90
b1	1.20	1.45	1.75
b2	1.17	1.27	1.37
c	0.40	0.50	0.60
c1	1.15	1.27	1.40
D	9.10	9.20	9.30
D1	7.63	7.93	8.23
E	10.05	10.25	10.45
E1	8.35	8.65	8.95
e	2.54BSC		
e1	5.08BSC		
H	14.61	15.00	15.88
L	1.78	2.35	2.79
L1	1.36REF		
L2	1.3REF		
L3	0.25REF		
All dimensions in millimeters			

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